

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JIAN GAO	07/24/2017
GENG HAN	07/24/2017
ILYA USVYATSKY	08/14/2017
JAMIN KANG	07/24/2017
HONGPO GAO	07/24/2017
JIBING DONG	07/25/2017
RECEIVING PARTY DATA	
Name:	EMC IP HOLDING COMPANY, LLC
Street Address:	176 SOUTH STREET
City:	HOPKINTON
State/Country:	MASSACHUSETTS
Postal Code:	01748
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15664730
CORRESPONDENCE DATA	
Fax Number:	(617)523-6850
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	6175235831
Email:	timothy.peng@hkclaw.com, patentdocketing@hkclaw.com
Correspondent Name:	HOLLAND & KNIGHT LLP
Address Line 1:	10 SAINT JAMES AVENUE
Address Line 4:	BOSTON, MASSACHUSETTS 02116
ATTORNEY DOCKET NUMBER:	113454.00269/108839
NAME OF SUBMITTER:	TIMOTHY PENG
SIGNATURE:	/Timothy Peng/
DATE SIGNED:	08/17/2017
Total Attachments: 8	

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ASSIGNMENT

WHEREAS, we, Jian Gao, Geng Han, Ilya Usvyatsky, Jamin King, Hongpo Gao and Jibing Dong have invented an invention comprising and/or embodying certain improvements or discoveries or both as described in an application for Letters Patent of the United States entitled Storage Device Group Split Technique for Extent Pool with Hybrid Capacity Storage Devices System and Method (Application), the specification of which:

- is being executed on even date herewith and is about to be filed in the United States Patent Office;
- was filed on July 31, 2017 as U.S. Application No. 15/664,730;
- was patented under U.S. Patent No. _____ on _____.

WHEREAS, EMC IP Holding Company, LLC (hereinafter "ASSIGNEE"), a corporation organized and existing under the laws of the State of Delaware and having a usual place of business at 176 South Street, Hopkinton, Massachusetts 01748 desires to acquire an interest therein in accordance with agreements duly entered into with us;

NOW, THEREFORE, to all whom it may concern be it known that for and in consideration of said agreements and of other good and valuable consideration, the receipt of which is hereby acknowledged, we have sold, assigned and transferred and by these presents do hereby sell, assign and transfer unto said ASSIGNEE, its successors, assigns and legal representatives, the entire right, title and interest in and throughout the United States of America, its territories and all foreign countries, in and to said invention as described in said application, together with the entire right, title and interest in and to said application and such Letters Patent as may issue thereon; said invention, application and Letters Patent to be held and enjoyed by said ASSIGNEE for its own use and behalf and for its successors, assigns and legal representatives, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held by us had this assignment and sale not been made; we hereby convey to ASSIGNEE all rights arising under or pursuant to any and all international agreements, treaties or laws relating to the protection of industrial property by filing any such applications for Letters Patent. We hereby acknowledge that this assignment, being of the entire right, title and interest in and to said invention, carries with it the right in ASSIGNEE to apply for and obtain from competent authorities in all countries of the world any and all Letters Patent by attorneys and agents of ASSIGNEE's selection and the right to procure the grant of all such Letters Patent to ASSIGNEE for its own name as assignee of the entire right, title and interest therein;

AND, we hereby further agree for ourselves and our executors and administrators to execute upon request any other lawful documents and likewise to perform any other lawful acts which may be deemed necessary to secure fully the aforesaid invention to said ASSIGNEE, its successors, assigns and legal representatives, but at its or their expense and charges, including the execution of applications for patents in foreign countries, and the execution of substitution,

reissue, divisional or continuation applications and preliminary or other statements and the giving of testimony in any interference or other proceeding in which said invention or any application or patent directed thereto may be involved;

AND, we do hereby authorize and request the Commissioner of Patents of the United States to issue such Letters Patent as shall be granted upon said application or applications based thereon to said ASSIGNEE, its successors, assigns, and legal representatives;

AND, we hereby authorize our attorneys, EMC Corporation, to insert here in parenthesis (_____) the application number and filing date of said Application (or foreign counterpart application) to facilitate the recording or other official processing of this Assignment.

IN TESTIMONY WHEREOF, we have hereunto set our hands and affixed our seals as set forth below:

Date: 2017.7.24



Inventor's Signature

Print full name of inventor

Jian Gao

Residence

Beijing, China

Citizenship

China

Mailing Address

601 Building 16, 305# Guanganmen Wai Street
Xicheng District
Beijing, China

I, Baote Zhuo (name of first witness), whose residential address is
7/F Block D Tsinghua Science Park Haidian District Beijing P.R.C
was personally present and did see Jian Gao (name of person signing the assignment), who is
personally known to me, execute the above assignment.

Baote Zhuo (signature of first witness)
Signed at 7/F Block D Tsinghua Science Park Haidian District Beijing P.R.C (location of witness signature)
on this day, 7.24, 2017 (date of signature).

I, Shaogin Gong (name of second witness), whose residential address is
7/F Block D Tsinghua Science Park Haidian District Beijing P.R.C
was personally present and did see Jian Gao (name of person signing the assignment), who is
personally known to me, execute the above assignment.

Shaogin Gong (signature of second witness)
Signed at 7/F Block D Tsinghua Science Park Haidian District Beijing (location of witness signature)
on this day, 7.25, 2017 (date of signature).

Date: 2017.7.24

Geng Han
Inventor's Signature

Print full name of inventor:

Geng Han

Residence:

Beijing, China

Citizenship:

China

Mailing Address:

1-601 Building 2, Block 1

Shangdi Dongli, Haidian

Beijing, China

I, Baote Zhuo (name of first witness), whose residential address is 2/F Block D, Tsinghua Science Park, Haidian District, Beijing, P.R.C was personally present and did see Geng Han (name of person signing the assignment), who is personally known to me, execute the above assignment.

Baote Zhuo (signature of first witness)
Signed at 2/F, Block D, Tsinghua Science Park, Haidian District, Beijing, P.R.C (location of witness signature)
on this day, 7.24, 2017 (date of signature).

I, Shangjin Gong (name of second witness), whose residential address is 7/E, Block D, Tsinghua Science Park, Haidian District, Beijing, P.R.C was personally present and did see Geng Han (name of person signing the assignment), who is personally known to me, execute the above assignment.

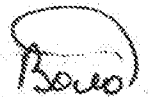
Shangjin Gong (signature of second witness)
Signed at 7/E, Block D, Tsinghua Science Park, Haidian District, Beijing (location of witness signature)
on this day, 7.25, 2017 (date of signature).

Date: 8/14/2017

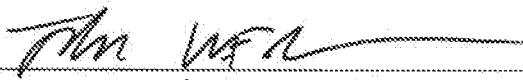

Inventor's Signature

Print full name of inventor: Ilya Usvyatsky
Residence: Northborough, MA
Citizenship: United States
Mailing Address: 1 Potter Circle
Northborough, MA 01532

I, Viktor Voloboi (name of first witness), whose residential address is
255 North Rd, Unit B, Chelmsford, MA
was personally present and did see Ilya Usvyatsky (name of person signing the assignment), who
is personally known to me, execute the above assignment.


Signed at Burlington, MA (location of witness signature)
on this day, 8/14, 2017 (date of signature).

John McClain
I, John W.F. McClain (name of second witness), whose residential address is
7 Frost Rd, Lexington MA
was personally present and did see Ilya Usvyatsky (name of person signing the assignment), who
is personally known to me, execute the above assignment.


Signed at Burlington MA (location of witness signature)
on this day, 8/14, 2017 (date of signature).

Date: 2017.7.24

康文斌
Inventor's Signature

Print full name of inventor: Jamin Kang
Residence: Beijing, China
Citizenship: China
Mailing Address: 902 Building 13, Wenhuiyuan, Haidian District
Beijing, China

I, Baste Zhuo (name of first witness), whose residential address is 7/F, Block D, Tsinghua Science Park, Haidian District, Beijing, P.R.C was personally present and did see Jamin Kang (name of person signing the assignment), who is personally known to me, execute the above assignment.

Baste Zhuo (signature of first witness)
Signed at 7/F, Block D, Tsinghua Science Park, Haidian District, Beijing, P.R.C (location of witness signature)
on this day, 7.24, 2017 (date of signature).

I, Shaojin Gong (name of second witness), whose residential address is 7/F, Block D, Tsinghua Science Park, Haidian District, Beijing, P.R.C was personally present and did see Jamin Kang (name of person signing the assignment), who is personally known to me, execute the above assignment.

Shaojin Gong (signature of second witness)
Signed at 7/F, Block D, Tsinghua Science Park, Haidian District, Beijing (location of witness signature)
on this day, 7.24, 2017 (date of signature).

Date: 2017.7.25

Hongpo Gao
Inventor's Signature

Print full name of inventor:

Hongpo Gao

Residence:

Beijing, China

Citizenship:

China

Mailing Address:

5-301 Building 1, Longyue Street No 10
Changping District
Beijing, China

I, Baote Zhuo (name of first witness), whose residential address is 7/F Block D, Tsinghua Science Park, Haidian District, Beijing, P.R.C. was personally present and did see Hongpo Gao (name of person signing the assignment), who is personally known to me, execute the above assignment.

Baote Zhuo (signature of first witness)
Signed at 7/F Block D, Tsinghua Science Park, Haidian District, Beijing, P.R.C. (location of witness signature)
on this day, 7.25, 2017 (date of signature).

I, Shaojin Gong (name of second witness), whose residential address is 7/F Block D, Tsinghua Science Park, Haidian District, Beijing, P.R.C. was personally present and did see Hongpo Gao (name of person signing the assignment), who is personally known to me, execute the above assignment.

Shaojin Gong (signature of second witness)
Signed at 7/F Block D, Tsinghua Science Park, Haidian District, Beijing (location of witness signature)
on this day, 7.25, 2017 (date of signature).

Date: 20 17. 7. 25

Jibing Dong
Inventor's Signature

Print full name of inventor:

Jibing Dong

Residence:

Beijing, China

Citizenship:

China

Mailing Address:

2-2903 Building 5, Zaoyuanxiang No. 3
Qingyuan Street, Daxing District
Beijing, China

I, Baote Zhuo (name of first witness), whose residential address is 7/F Block D Tsinghua Science Park, Haidian District, Beijing, P.R.C was personally present and did see Jibing Dong (name of person signing the assignment), who is personally known to me, execute the above assignment.

Baote Zhuo (signature of first witness)
Signed at 7/F, Block D, Tsinghua Science Park, Haidian District, Beijing, P.R.C (location of witness signature)
on this day, 7. 25, 2017 (date of signature).

I, Shaojin Gong (name of second witness), whose residential address is 7/F, Block D, Tsinghua Science Park, Haidian District, Beijing, P.R.C was personally present and did see Jibing Dong (name of person signing the assignment), who is personally known to me, execute the above assignment.

Shaojin Gong (signature of second witness)
Signed at 7/F, Block D, Tsinghua Science Park, Haidian District, Beijing (location of witness signature)
on this day, 7. 25, 2017 (date of signature).